



67,200-506

Serial Number 09/920,911

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#4/Response  
11-22-02  
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**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

**TO:** ASSISTANT COMMISSIONER FOR PATENTS  
Washington, D.C. 20231

**FROM:** Tung & Associates  
838 West Long Lake Road - Suite 120  
Bloomfield Hills, MI 48302

**DATE:** 24 October 2002

**REF:** Applicant : Yu et al. Filing Date : 2 August 2001  
Serial No : 09/920,911 Att'y No. : 67,200-506  
Art Unit : 2812 Examiner : Richard A. Booth  
Title : Thermal Compensation Method for Forming Semiconductor  
Integrated Circuit Microelectronic Fabrication

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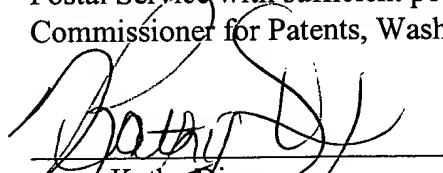
**RESPONSE TO OFFICE ACTION**

Sir:

In response to an office action mailed on 24 September 2002, please consider the following remarks pertaining to the above referenced application.

**CERTIFICATE OF MAILING**

I hereby certify that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail in an envelope addressed to the Assistant Commissioner for Patents, Washington D.C., 20231 on 11/1 2002

  
Kathy Dixon

11/1/02  
Date